

CLAIM AMENDMENTS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 - 15 (canceled).

Claim 16 (currently amended). An optical module, comprising:

a circuit carrier;

a housing including at least sections with a ring-shaped support formed thereon, said housing disposed on said circuit carrier, said ring-shaped support defining an outer boundary of said housing;

a semiconductor element disposed in said housing; and

a lens unit configured for projecting electromagnetic radiation onto said semiconductor element, said lens unit including a base lens;

wherein said semiconductor element and said lens unit are formed in two parts, said base lens includes at least sections formed with a collar that has a shape corresponding to said ring-shaped support that is formed on said housing, and said collar of said base lens is directly supported on said ring-shaped support that is formed on said housing; and

wherein said lens unit includes a lens holder and said lens holder is supported by said circuit carrier substantially without being supported by said housing, and

wherein said base lens is disposed externally from said housing.

Claims 17 - 22 (canceled).

Claim 23 (new). The optical module according to claim 16, wherein said outer boundary of said housing, which is defined by said ring-shaped support, is external to all portions that are integrally formed with said housing.

Claim 24 (new). The optical module according to claim 16, wherein said housing is not disposed between said lens holder and said base lens.

Claim 25 (new). The optical module according to claim 16, wherein said housing protects said semiconductor element from infrared radiation.

Claim 26 (new). The optical module according to claim 16, wherein said housing and said semiconductor element form an integral unit that does not package said base lens.